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Attorney Docket No. 450101-02921

Applicant Kondo, et al.

SIGNAL PROCESSING METHOD AND APPARATUS For

AND RECORDING MEDIUM

PCT/JP00/09421 Corresponding Int'l Appln.

December 28, 2000 International Filing Date

Commissioner of Patents and Trademarks

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5.01.01

Tetsujiro KONDO, Junichi ISHIBASHI, 1. Names of Conveying Parties

Takashi SAWAO, Seiji WADA, Tohru MIYAKE, Takahiro NAGANO, Naoki

FUJIWARA

Sony Corporation Names and addresses of receiving parties 2.

7-35, Kitashinagawa 6-chome

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JAPAN

3.	Nature of Conveyance	:	Assignment.
0.	Execution Dates		March 15, 12, 12, 12, 14, 12, 14, 2001

Application No.: 4.

: 14

This document is being filed together with a new application, the execution date of the

application is: March 15, 12, 12, 12, 14, 12, 14, 2001

Name and address of party to whom the recorded assignment and any correspondence concerning 5.

the document should be mailed:

09830858 William S. Frommer

Registration No. 25,506

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Fifth Avenue

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Total number of applications and patents involved: <u>1</u>. 6.

Total Fee (37 CFR 3.41): \$40.00 7.

Fee enclosed, Check No _15341

Charge Fee Deposit Account No. 50-0320 (Attach duplicate copy of this page if paying by deposit 8.

If any additional fee is required, authorization is hereby given to charge \times Deposit Account No. 50-0320.

9.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy

is a true copy of the original document.

(Reg. No. 25,506) William S. Frommer, Esq.

Name of Person Signing

Signature

dds0159

PATENT REEL: 012378 FRAME: 0786

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

SIGNAL PROCESSING METHOD AND APPARATUS AND RECORDING MEDIUM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35, Kitashinaqawa 6-chome, Shinaqawa-ku, Tokyo 141-0001 Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: <a href="https://pcc.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.ncber.n

This assignment executed on the dates indicated below.

etsujiro KONDO Name of first or sole inventor	Execution date of U.S. Patent Application
Residence of first or sole inventor Titulia tonology Signature of first or sole inventor	March. 15, 200 Date of this assignment
Junichi ISHIBASHI Name of second inventor	Execution date of U.S. Patent Application
Residence of second inventor Signature of second inventor	March 12.200

PAFTERT 1 of ^
REEL: 012378 FRAME: 0787

Takashi SAWAO	
Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of third inventor	
Jakashi SAWAO.	March 12,2001
Signature of third inventor	Date of this assignment
Seiji WADA	
Name of fourth inventor	Execution date of U.S. Patent Application
Kanagawa, Japan	
Residence of fourth inventor	March 12, 2001
Seigh Wada	maron (2, 200)
Signature of fourth inventor	Date of this assignment
Tohru MIYAKE	
Name of fifth inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of fifth inventor	March 14, 2001
John Mycke	
Signature of fifth inventor	Date of this assignment
Takahiro NAGANO	Execution date of U.S. Patent Application
Name of sixth inventor	Execution date of our i
Kanagawa, Japan	
Residence of sixth inventor	March 12, 2001
Tokahiro Nagano	Date of this assignment
Signature of sixth inventor	
Naoki FUJIWARA	Execution date of U.S. Patent Application
Name of seventh inventor	
Tokyo, Japan	
Residence of seventh inventor	March 14.2001
Marki Jujuvara	Date of this assignment

Signature of seventh inventor